

DATA SHEET

NEC

PHOTOCOUPLER

PS2503-1,-2,-4,PS2503L-1,-2,-4

LOW INPUT CURRENT, HIGH SPEED SWITCHING MULTI PHOTOCOUPLER SERIES

-NEPOC Series-

DESCRIPTION

The PS2503-1, -2, -4 and PS2503L-1, -2, -4 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon phototransistor.

The PS2503-1, -2, -4 are in a plastic DIP (Dual In-line Package) and the PS2503L-1, -2, -4 are lead bending type (Gull-wing) for surface mount.

FEATURES

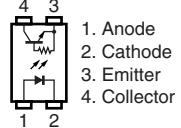
- High isolation voltage ($BV = 5\,000\,V_{r.m.s.}$)
- High-speed switching ($t_r = 20\,\mu s$ TYP., $t_f = 30\,\mu s$ TYP.)
- Ordering number of tape product: PS2503L-1-E3, E4, F3, F4, PS2503L-2-E3, E4
- Safety standards
 - UL approved: File No. E72422
 - CSA approved: No. CA 101391

APPLICATIONS

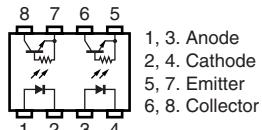
- Measurement equipment
- Programmable logic controller
- Telephone/Telegraph Receiver
- Power supply

PIN CONNECTION (Top View)

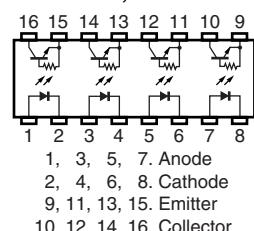
PS2503-1, PS2503L-1



PS2503-2, PS2503L-2



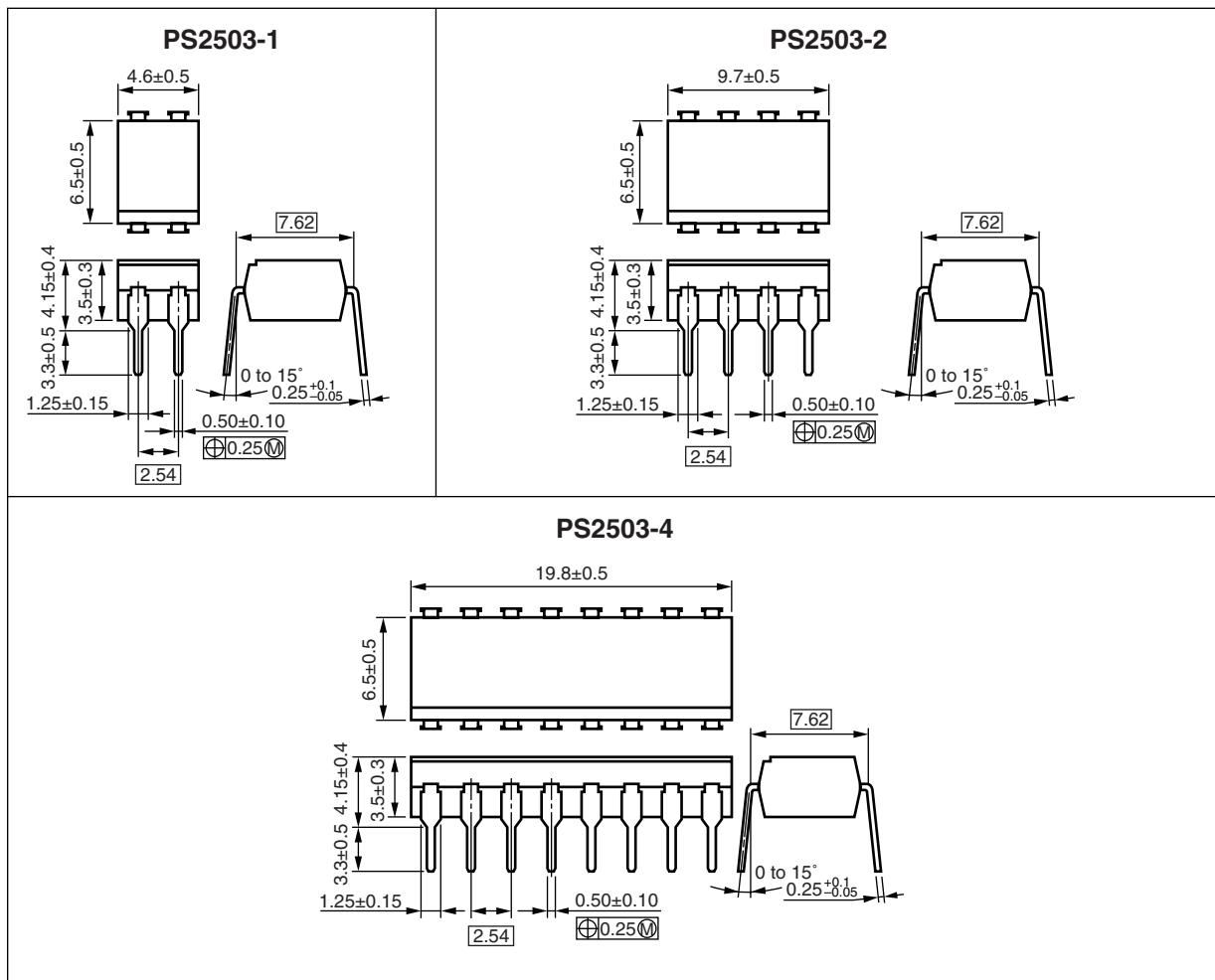
PS2503-4, PS2503L-4



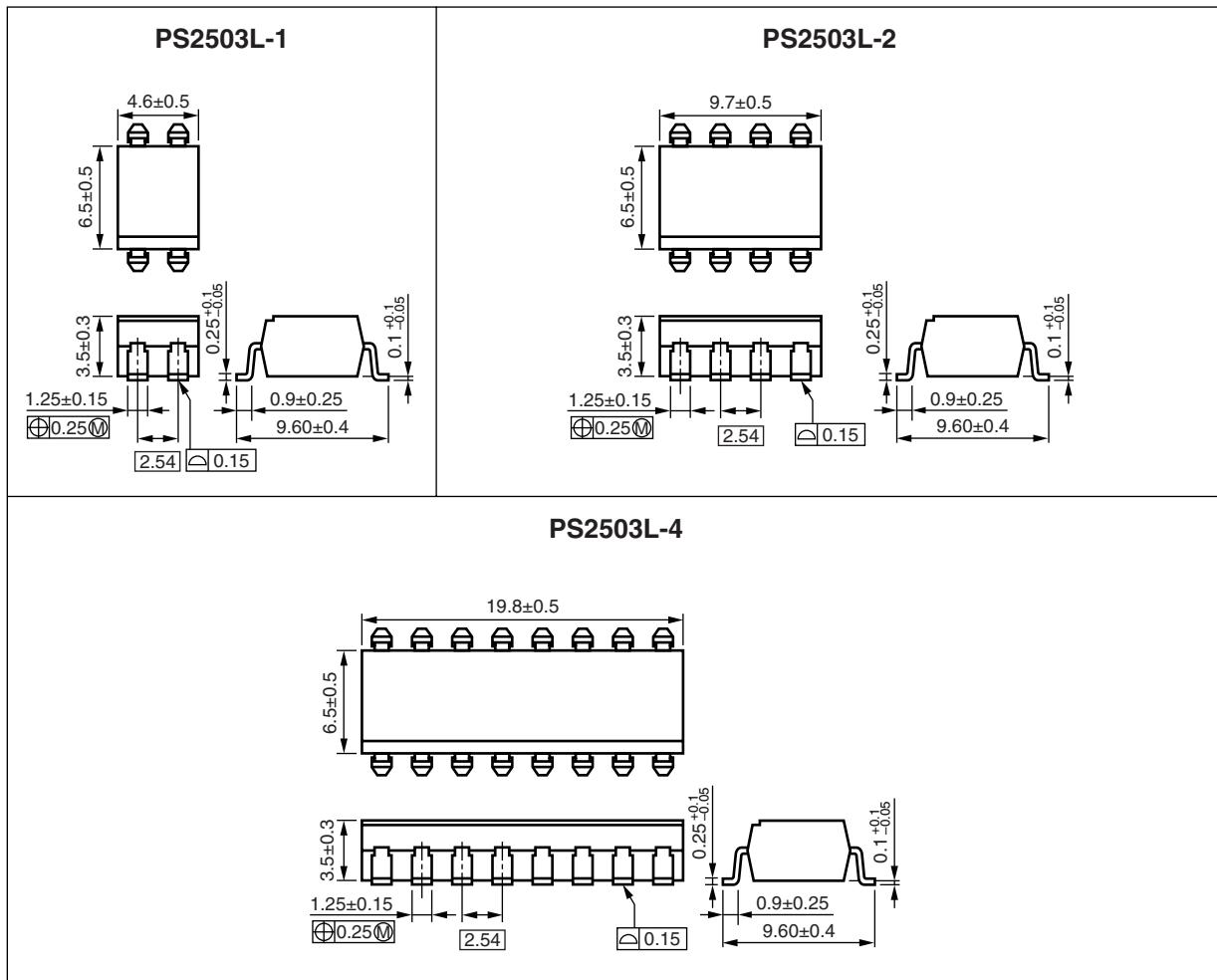
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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

PACKAGE DIMENSIONS (UNIT : mm)

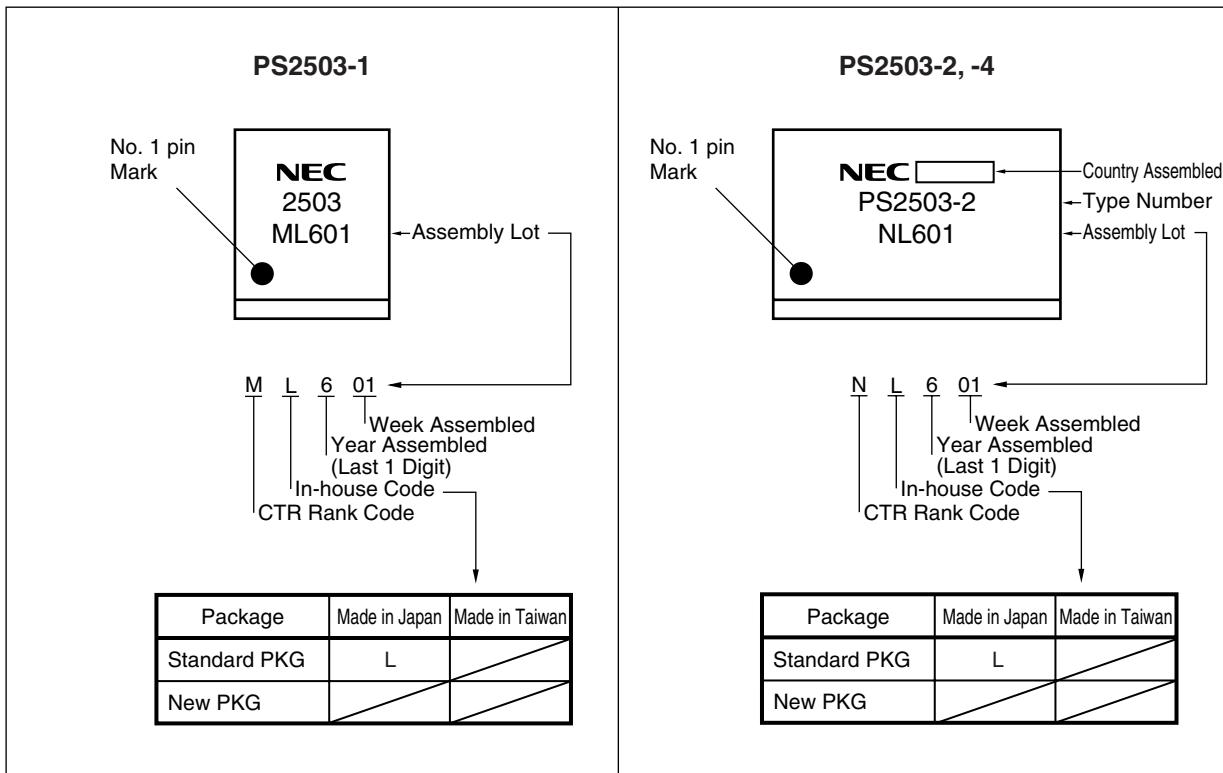
DIP Type



Lead Bending Type



★ MARKING EXAMPLE



★ ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ¹
PS2503-1	PS2503-1-A	Pb-Free	Magazine case 100 pcs	Standard products (UL, CSA Approved)	PS2503-1
PS2503L-1	PS2503L-1-A		Embossed Tape 1 000 pcs/reel		
PS2503L-1-E3	PS2503L-1-E3-A		Embossed Tape 2 000 pcs/reel		
PS2503L-1-E4	PS2503L-1-E4-A		Magazine case 45 pcs		
PS2503L-1-F3	PS2503L-1-F3-A		Embossed Tape 1 000 pcs/reel		
PS2503L-1-F4	PS2503L-1-F4-A		Magazine case 20 pcs		
PS2503-2	PS2503-2-A				
PS2503L-2	PS2503L-2-A				
PS2503L-2-E3	PS2503L-2-E3-A				
PS2503L-2-E4	PS2503L-2-E4-A				
PS2503-4	PS2503-4-A				
PS2503L-4	PS2503L-4-A				

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings		Unit
			PS2503-1, PS2503L-1	PS2503-2,-4 PS2503L-2,-4	
Diode	Reverse Voltage	V _R	6		V
	Forward Current (DC)	I _F	80		mA/ch
	Power Dissipation Derating	ΔP _D /°C	1.5	1.2	mW/°C
	Power Dissipation	P _D	150	120	mW/ch
	Peak Forward Current ¹	I _{FP}	1		A/ch
Transistor	Collector to Emitter Voltage	V _{CEO}	40		V
	Emitter to Collector Voltage	V _{E_{CO}}	0.6		V
	Collector Current	I _C	30		mA/ch
	Power Dissipation Derating	ΔP _C /°C	1.5	1.2	mW/°C
	Power Dissipation	P _C	150	120	mW/ch
Isolation Voltage ²		BV	5 000		Vr.m.s.
Operating Ambient Temperature		T _A	-55 to +100		°C
Storage Temperature		T _{stg}	-55 to +150		°C

*1 PW = 100 μs, Duty Cycle = 1%

*2 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output

Pins 1-2 shorted together, 3-4 shorted together (PS2503-1, PS2503L-1).

Pins 1-4 shorted together, 5-8 shorted together (PS2503-2, PS2503L-2).

Pins 1-8 shorted together, 9-16 shorted together (PS2503-4, PS2503L-4).

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	$I_F = 1 \text{ mA}$		1.1	1.3	V
	Reverse Current	I_R	$V_R = 5 \text{ V}$			5	μA
	Terminal Capacitance	C_t	$V = 0 \text{ V}, f = 1.0 \text{ MHz}$		50		pF
Transistor	Collector to Emitter Dark Current	I_{CEO}	$V_{CE} = 40 \text{ V}, I_F = 0 \text{ mA}$			100	nA
Coupled	Current Transfer Ratio (I_C/I_F) ¹	CTR	$I_F = 1 \text{ mA}, V_{CE} = 5 \text{ V}$	100	200	400	%
	Collector Saturation Voltage	$V_{CE(\text{sat})}$	$I_F = 1 \text{ mA}, I_C = 0.2 \text{ mA}$			0.25	V
	Isolation Resistance	R_{I-O}	$V_{I-O} = 1.0 \text{ kV}_{\text{DC}}$	10^{11}			Ω
	Isolation Capacitance	C_{I-O}	$V = 0 \text{ V}, f = 1.0 \text{ MHz}$		0.5		pF
	Rise Time ²	t_r	$V_{CC} = 5 \text{ V}, I_F = 1 \text{ mA}, R_L = 10 \text{ k}\Omega$		20		μs
	Fall Time ²	t_f			30		

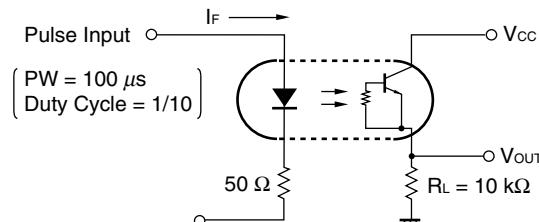
*1 CTR rank (only PS2503-1, PS2503L-1)

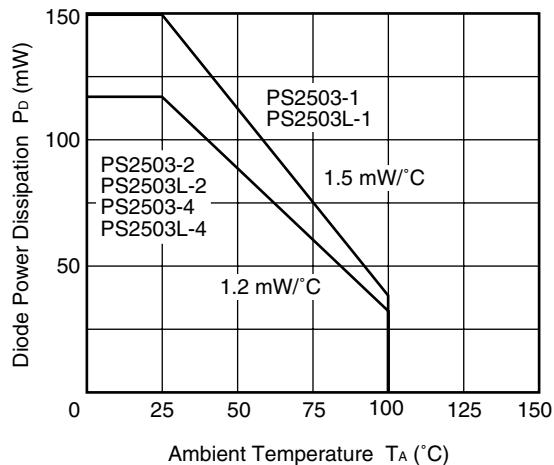
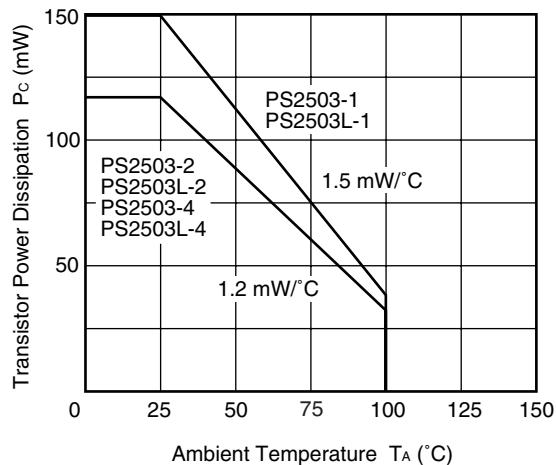
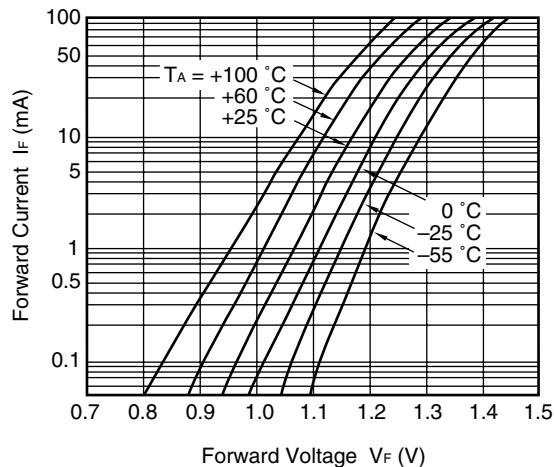
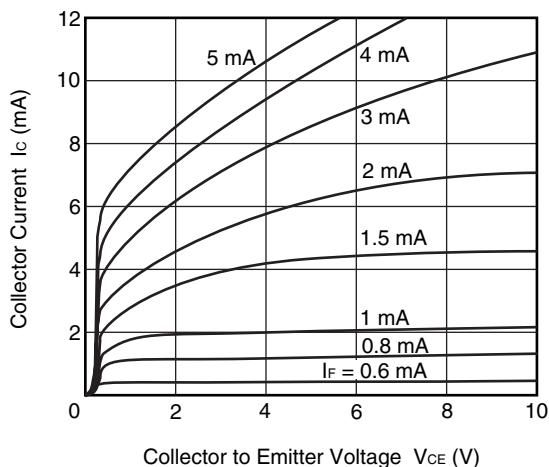
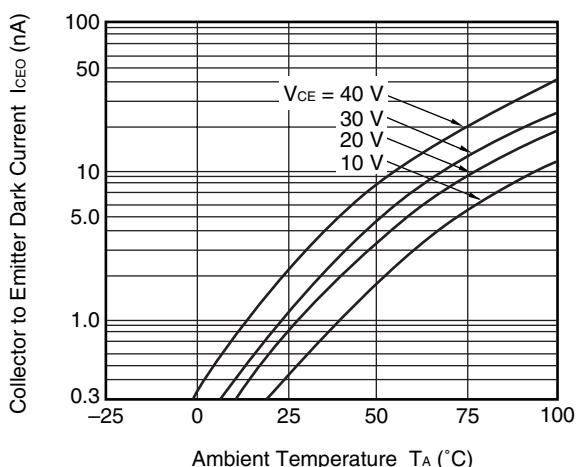
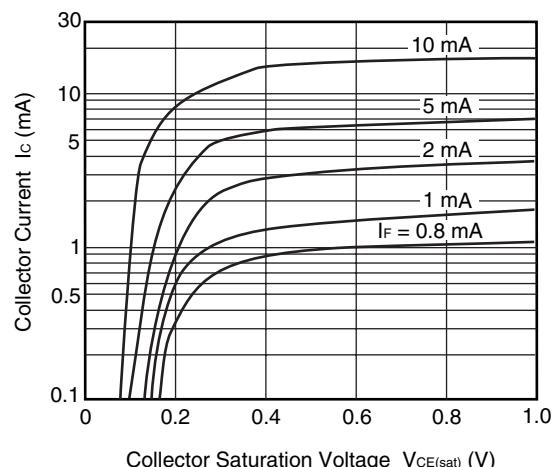
K : 200 to 400 (%)

L : 150 to 300 (%)

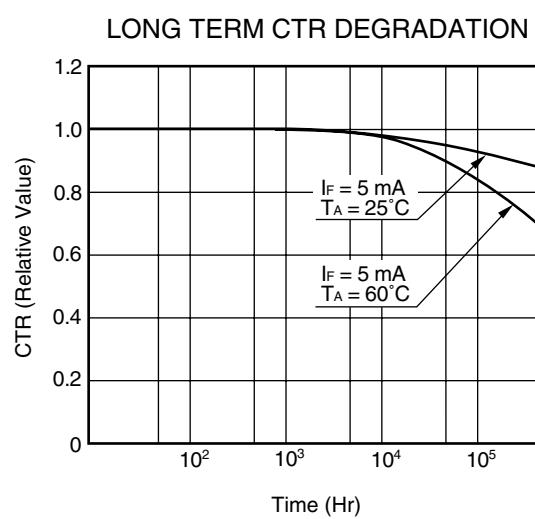
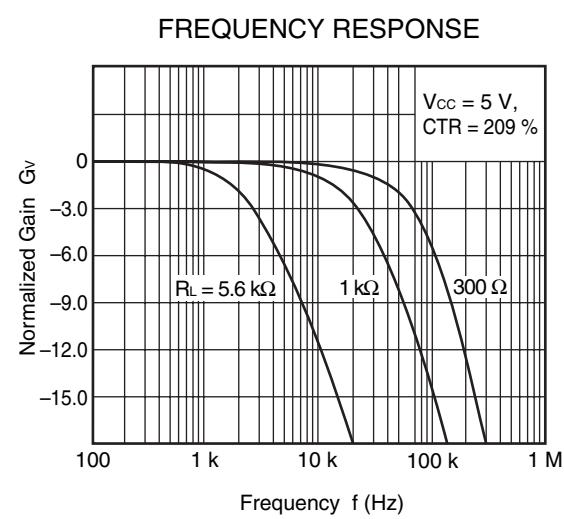
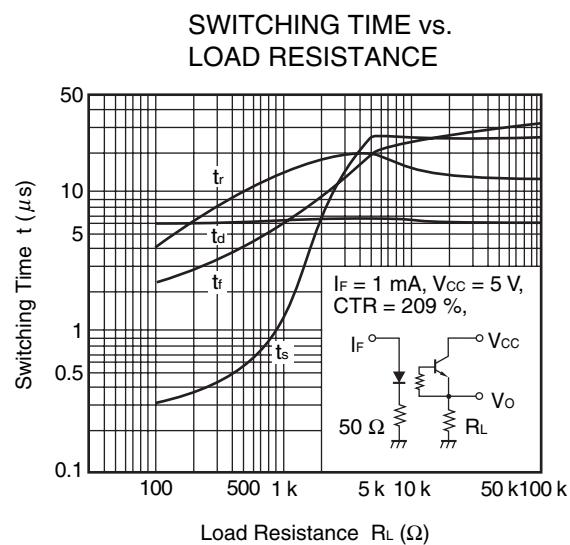
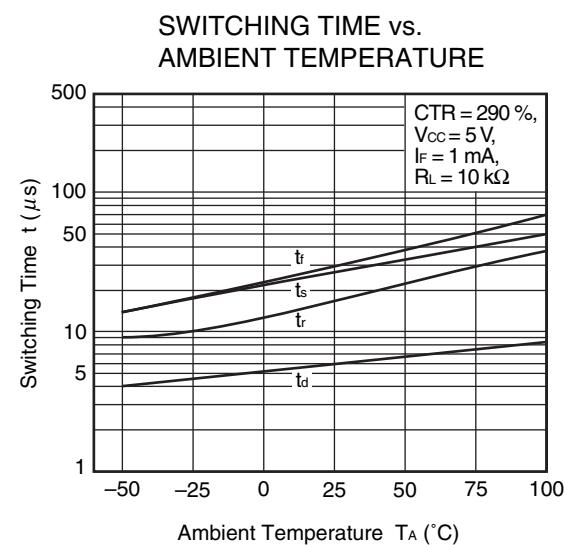
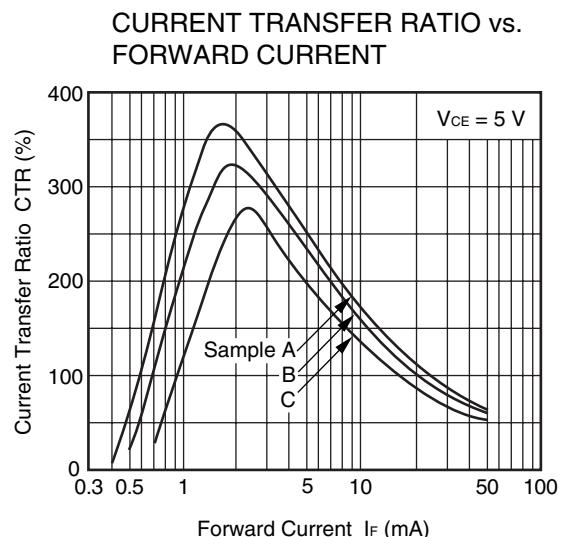
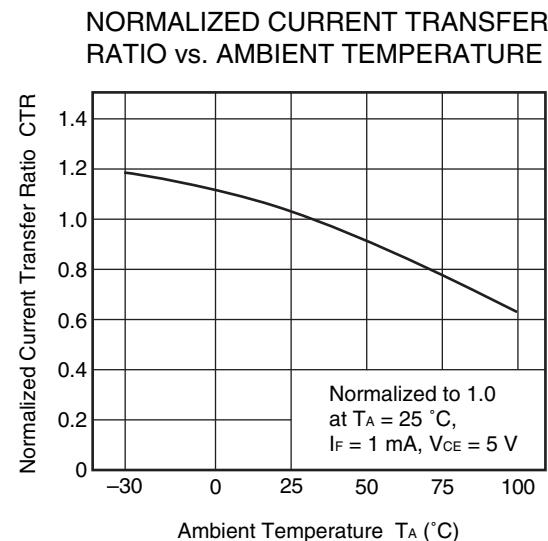
M : 100 to 200 (%)

*2 Test circuit for switching time



TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)DIODE POWER DISSIPATION vs.
AMBIENT TEMPERATURETRANSISTOR POWER DISSIPATION
vs. AMBIENT TEMPERATUREFORWARD CURRENT vs.
FORWARD VOLTAGECOLLECTOR CURRENT vs.
COLLECTOR TO Emitter VOLTAGECOLLECTOR TO Emitter DARK
CURRENT vs. AMBIENT TEMPERATURECOLLECTOR CURRENT vs.
COLLECTOR SATURATION VOLTAGE

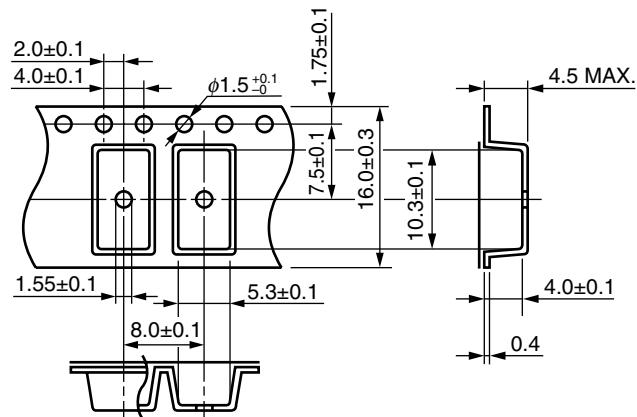
Remark The graphs indicate nominal characteristics.



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TAPING SPECIFICATIONS (UNIT : mm)

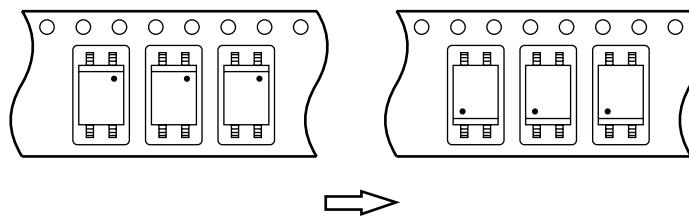
Outline and Dimensions (Tape)



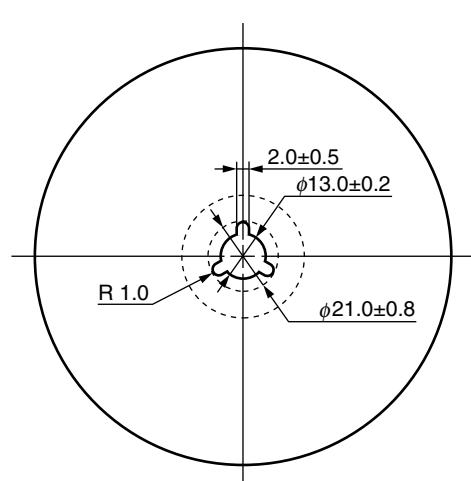
Tape Direction

PS2503L-1-E3

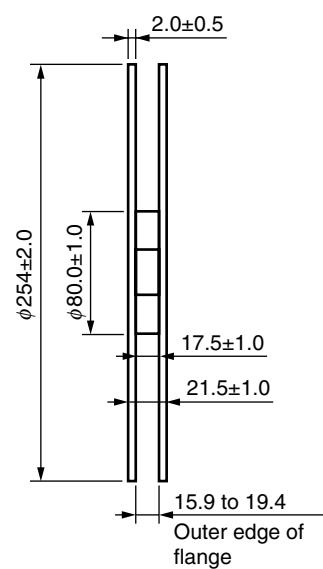
PS2503L-1-E4



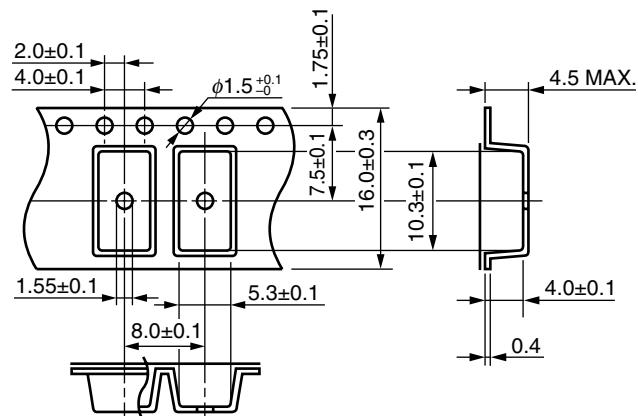
Outline and Dimensions (Reel)



Packing: 1 000 pcs/reel

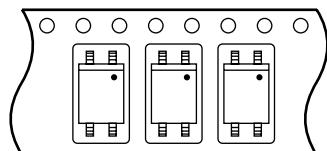


Outline and Dimensions (Tape)

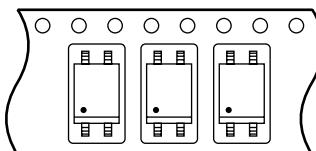


Tape Direction

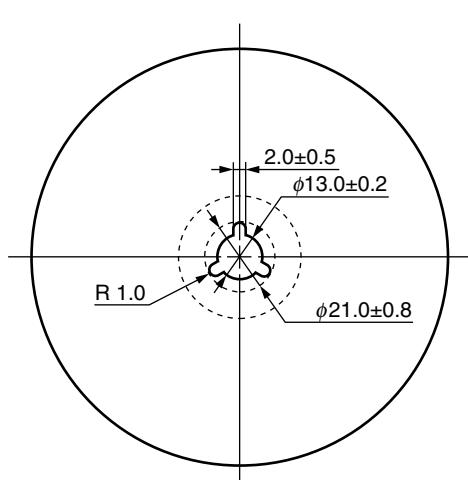
PS2503L-1-F3



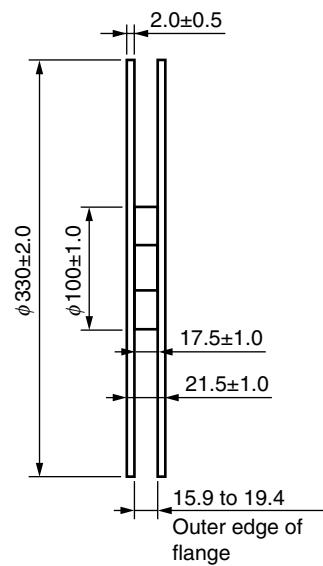
PS2503L-1-F4



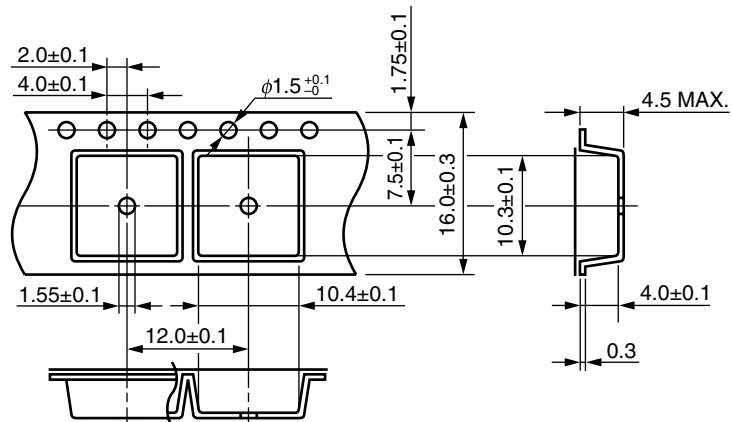
Outline and Dimensions (Reel)



Packing: 2 000 pcs/reel

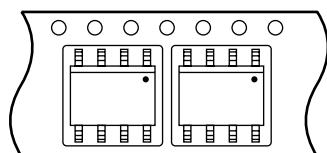


Outline and Dimensions (Tape)

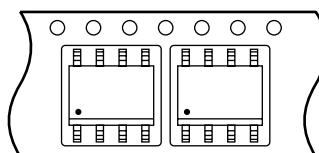


Tape Direction

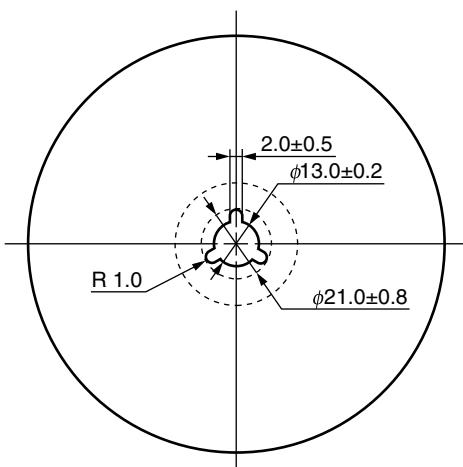
PS2503L-2-E3



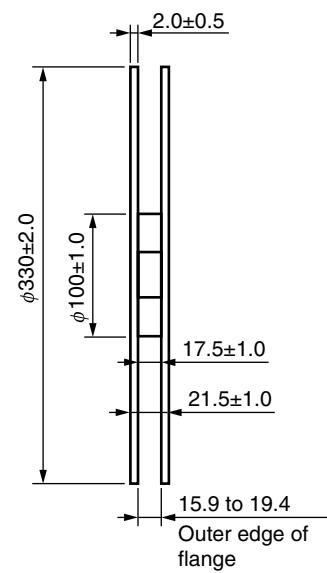
PS2503L-2-E4



Outline and Dimensions (Reel)



Packing: 1 000 pcs/reel



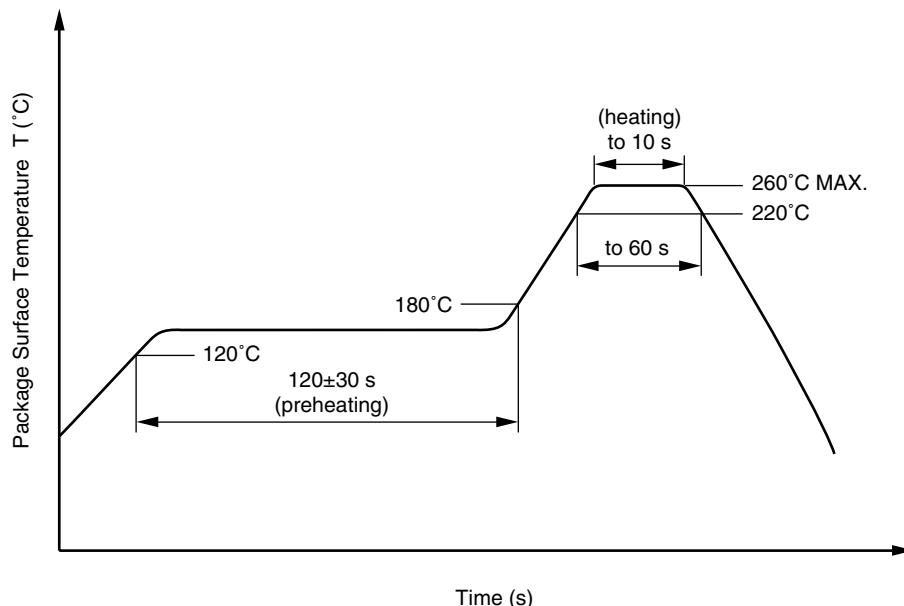
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

• Peak reflow temperature	260°C or below (package surface temperature)
• Time of peak reflow temperature	10 seconds or less
• Time of temperature higher than 220°C	60 seconds or less
• Time to preheat temperature from 120 to 180°C	120±30 s
• Number of reflows	Three
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature	260°C or below (molten solder temperature)
• Time	10 seconds or less
• Preheating conditions	120°C or below (package surface temperature)
• Number of times	One (Allowed to be dipped in solder including plastic mold portion.)
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

★ (3) Soldering by soldering iron

• Peak temperature (lead part temperature)	350°C or below
• Time (each pins)	3 seconds or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

★ 3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

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M8E 00.4-0110

Caution**GaAs Products**

This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
- 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

►For further information, please contact

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